450mA 23W Constant Current Buck LED Driver Micro-Module

Check for Samples: TPS92551, TPS92551EVM

FEATURES

- **Integrated All Power Components Including the Power Inductor**
- **Wide Input Voltage Range : 4.5V - 60V**
- **Constant Switching Frequency at 800kHz**
- **High Contrast Ratio (Minimum Dimming Current Pulse width < 16μs)**
- **Drives up to 16 LEDs in series at 60V input**
- **±3.5% Typical LED Current Accuracy**
- **LED Current Adjustable from 300mA to 450mA**
- **Up to 95% Efficiency**
- **TPS92551 Modules can be Connected in Parallel for Higher Current Operation**
- **Input Under-Voltage Lock-Out (UVLO)**
- **Compatible with Ceramic and Low ESR Capacitors**
- **Low Electro Magnetic Interference (EMI) Complies with EN55015 Standard** (1)
- **LED Open and Short Circuit Protections**
- **Thermal Shutdown and RoHS Compliant**
- **-40˚C to +125˚C Junction Temperature Range**

APPLICATIONS

- **General Lighting, Desk Lamps**
  - **Cabinet Lamps**
  - **Decorative Lamps**
  - **Street Lamps**
- **Architecture Lighting, Recess Lights**
  - **Spot Lights**
  - **Underwater Lights**

PACKAGE HIGHLIGHTS

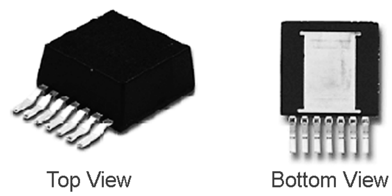
- **7-Lead Easy-to-Use Package (Similar to TO-263)**
- **Single Exposed Die Attach Pad for Enhanced Thermal Performance**
- **10.2 x 13.8 x 4.6 mm Package**

(1) EN55015, refer to Figure 35 and Figure 36

DESCRIPTION

The TPS92551 Constant Current Buck LED Driver Micro-Module drives maximum 450mA LED current up to 16 LEDs in a single string (maximum 23W). It integrates all the power components including the power inductor. The TPS92551 provides a full turn-key, highly efficient solution for wide range of single string LED lighting applications with up to 95% power efficiency. It accepts an input voltage ranging from 4.5V to 60V and delivers a 350mA LED current as default. The LED current is adjustable from 300mA to 450mA by charging a single external resistor.

The module operates at constant switching frequency (800kHz) with low Electro Magnetic Interference(EMI) complying with EN55015 standard. The module has fast control loop to realize fine LED current pulse yielding 256–step PWM dimming resolution at 240Hz for general lighting. Protection features include thermal shutdown, input under-voltage lockout, LED open-circuit and short-circuit protections. The TPS92551 Micro-Module is available in 7-pin PFM power package.



(1) θ_{JA} measured on a 1.705" x 3.0" four layer board, with one ounce copper , thirty five 12 mil thermal vias, no air flow, and 1W power dissipation.

Figure 1. 7-Pin PFM Package
10.16 x 13.77 x 4.57 mm (0.4 x 0.39 x 0.18 in)
θ_{JA} = 20°C/W, θ_{JC} = 1.9°C/W(1)
RoHS Compliant

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

System Performance

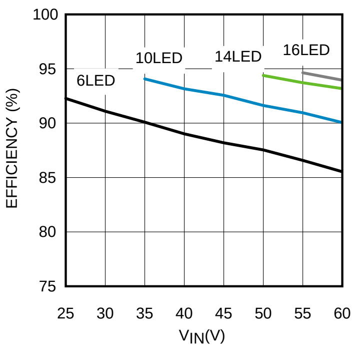


Figure 2. Efficiency vs V_{IN} , I_{LED} = 350mA

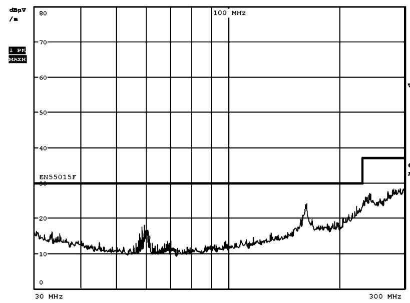


Figure 3. Radiated Emissions (EN 55015)

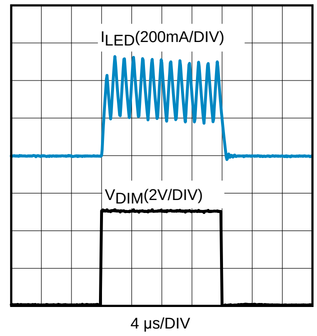
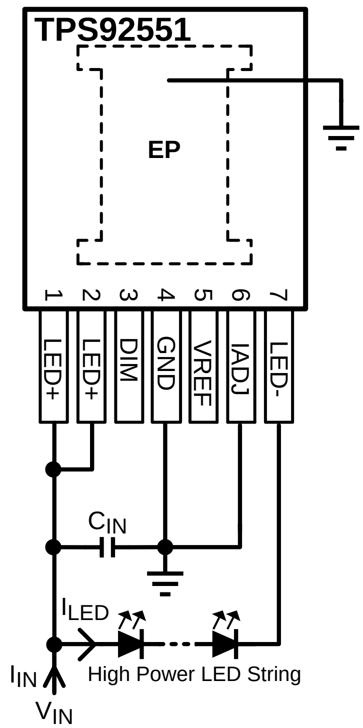


Figure 4. LED Current with PWM Dimming 16µs dimming pulse

TYPICAL APPLICATION CIRCUIT



CONNECTION DIAGRAM

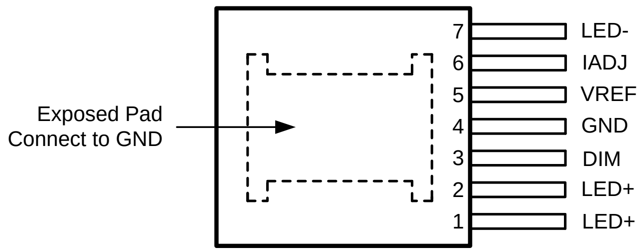


Figure 5. 7-Pin PFM (Top View)
See NDW0007A Package

PIN DESCRIPTIONS

Pin Number	Name	Description	Function
1, 2	LED+	Anode of LED string	Supply input and rail connection to the anode of the LED string.
3	DIM	Dimming signal input	Dimming control signal input. Open to enable or apply logic level PWM signal to control the brightness of the LED string.
4	GND	Ground	Reference point for all stated voltages. Connect to the exposed pad of the package externally.
5	VREF	Voltage reference	Internal voltage reference output.
6	IADJ	LED current adjustment	Fine tunning of the LED current by connecting a resistor between this pin and ground. Connect this pin to ground for factory preset current.
7	LED-	Cathode of LED string	The current return pin of the LED string, connect to the cathode of the LED string.
EP	Exposed Pad	Exposed thermal pad	Used to dissipate heat from the package during operation. Must connect to GND directly.

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS (1)

If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.

	VALUE / UNITS
LED+, LED– to GND	-0.3V to 67V
DIM to GND	-0.3V to 6V
IADJ, VREF to GND	-0.3V to 5V
ESD Susceptibility (2)	±2 kV (All Pins Except Pin 6)
Power Dissipation	Internally Limited
Junction Temperature	150°C
Storage Temperature Range	0°C to 150°C
Peak Reflow Case Temperature (30 sec)	245°C

(1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions under which operation of the device is intended to be functional. For ensured specifications and test conditions, see the Electrical Characteristics.
(2) The human body model is a 100 pF capacitor discharged through a 1.5 kΩ resistor into each pin. The Pin 6 (IADJ pin) pass ± 1kV.Test method is per JESD22-AI14S.

RECOMMENDED OPERATING CONDITIONS (1)

	VALUE / UNITS
LED+, LED-	4.5V to 60V
DIM	0V to 5.5V
IADJ	0V to 0.2V
Junction Temperature (T_J)	–40°C to 125°C

(1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions under which operation of the device is intended to be functional. For ensured specifications and test conditions, see the Electrical Characteristics.

ELECTRICAL CHARACTERISTICS

Limits in standard type are for T_J = 25°C unless otherwise stated; limits in **boldface** type apply over the operating junction temperature range T_J of -40°C to 125°C. Minimum and maximum limits are specified through test, design, or statistical correlation. Typical values represent the most likely parametric norm at T_J = 25°C, and are provided for reference purposes only. Unless otherwise stated the following conditions apply: V_{IN} =48 V, I_{LED} = 350mA. V_{IN} is the voltage applied across LED+ and GND. I_{IN} is the input current flowing into the LED+ node. I_{LED} is a LED current flowing into the LED- pin. V_{LED} is the voltage applied across LED+ and LED-. V_{DIM} is the voltage applied across the DIM pin to ground. Resistor R_{IADJ} connect from IADJ pin to ground. Resistor R_{VREF} connect from VREF pin to ground.

Symbol	Parameter	Conditions	Min (1)	Typ (2)	Max (1)	Units
SYSTEM PARAMETERS						
I_{IN}	Input Current	V_{LED} = 0V, 4.5V ≤ V_{IN} ≤ 60V, V_{DIM} = 0V	2.1	2.65	3.0	mA
I_{LED}	LED Current	V_{LED} = 24V , R_{IADJ} = 0Ω, R_{VREF} = open, T_J = 25°C	340	350	364	mA
		V_{LED} = 24V, R_{IADJ} = 0Ω, R_{VREF} = open, T_J = 25°C to 125°C	337	350	364	
		V_{LED} = 24V, R_{IADJ} = 0Ω , R_{VREF} = open, T_J = -40°C to 125°C	**337**	350	**371**	
$I_{LED–60V}$	LED Current at V_{IN} = 60V	V_{IN} = 60V, V_{LED} = 36V, R_{IADJ} = 0Ω R_{VREF} = open, T_J = 25°C	342	350	367	mA
		V_{IN} = 60V, V_{LED} = 36V, R_{IADJ} = 0Ω, R_{VREF} = open, T_J = 25°C to 125°C	338	350	367	
		V_{IN} = 60V, V_{LED} = 36V, R_{IADJ} = 0Ω, R_{VREF} = open, T_J = -40°C to 125°C	**338**	350	**374**	
$I_{LED-ADJ1}$	Adjusted LED Current	V_{LED} = 24V, R_{IADJ} = 0Ω, R_{VREF} = 10.5kΩ, T_J = 25°C	442	450	471	mA
		V_{LED} = 24V, R_{IADJ} = 0Ω, R_{VREF} = 10.5kΩ, T_J = 25°C to 125°C	437	450	471	
		V_{LED} = 24V, R_{IADJ} = 0Ω, R_{VREF} = 10.5kΩ, T_J = -40°C to 125°C	**437**	450	**483**	
$I_{LED-ADJ2}$	Adjusted LED Current	V_{LED} = 24V, R_{IADJ} = 500Ω, R_{VREF} = open, T_J = 25°C	288	300	309	mA
		V_{LED} = 24V, R_{IADJ} = 500Ω, R_{VREF} = open, T_J = 25°C to 125°C	282	300	309	
		V_{LED} = 24V, R_{IADJ} = 500Ω, R_{VREF} = open, T_J = -40°C to 125°C	**282**	300	**316**	
$I_{LED-SHORT}$	LED Short Circuit Current at V_{IN} = 60V	V_{LED} = 0V, V_{IN} = 60V, DIM = open	**800**	920	**1020**	mA
$I_{LED-LEAK}$	"LED-" pin leakage current	V_{LED} = 0V, V_{IN} = operating max, DIM = 0V			1.2	µA
f_{SW}	Switching Frequency	V_{LED} = 24V, R_{IADJ} = 0Ω, R_{VREF} = open	**720**	800	**920**	kHz
V_{DIM}	DIM Pin Threshold	V_{DIM} Increasing		1.0	**1.3**	V
$V_{DIM-HYS}$	DIM Pin Hysteresis			0.25		V
THERMAL CHARACTERISTICS						
T_{SD}	Thermal Shutdown Temperature	T_J Rising		170		°C
T_{SD-HYS}	Thermal Shutdown Temp. Hysteresis	T_J Rising		10		°C
θ_{JA}	Junction to Ambient(3)	4 Layer JEDEC Printed Circuit Board, 100 vias, No air flow		19.3		°C/W
		2 Layer JEDEC PCB, No air flow		21.5		
θ_{JC}	Junction to Case	No air flow		1.9		°C/W

(1) Min and Max limits are 100% production tested at an ambient temperature (T_A) of 25°C. Limits over the operating temperature range are specified through correlation using Statistical Quality Control (SQC) methods. Limits are used to calculate Average Outgoing Quality Level (AOQL).
(2) Typical numbers are at 25°C and represent the most likely parametric norm.
(3) θ_{JA} measured on a 1.705" x 3.0" four layer board, with one ounce copper , thirty five 12 mil thermal vias, no air flow, and 1W power dissipation.

TYPICAL PERFORMANCE CHARACTERISTICS

Unless otherwise specified, the following conditions apply: V_{IN} = 48V, C_{IN} is a 2.2µF 100V X7R ceramic capacitor for driving 5–13 power LEDs with I_{LED} = 350mA. Single LED forward voltage used is 3.2V. T_A = 25°C for efficiency curves and waveforms.

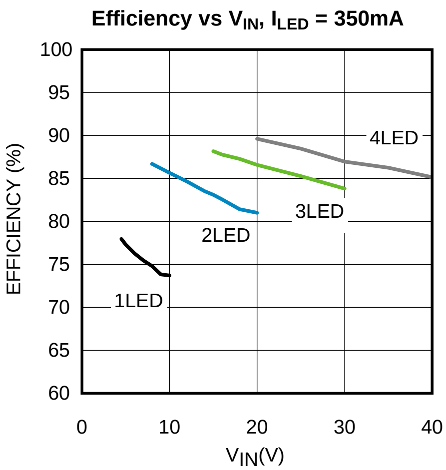


Figure 6.

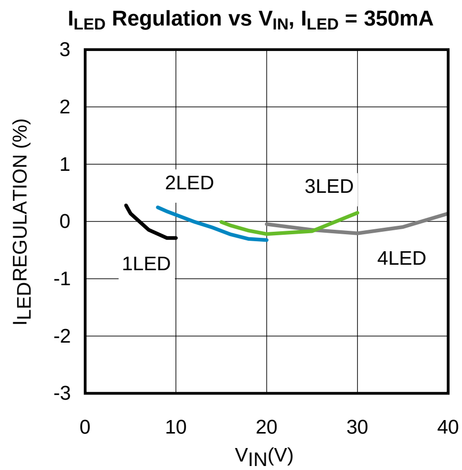


Figure 7.

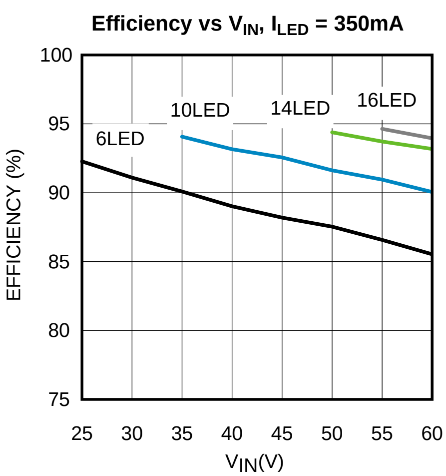


Figure 8.

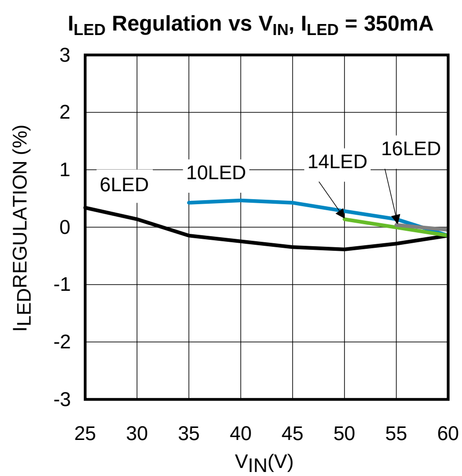


Figure 9.

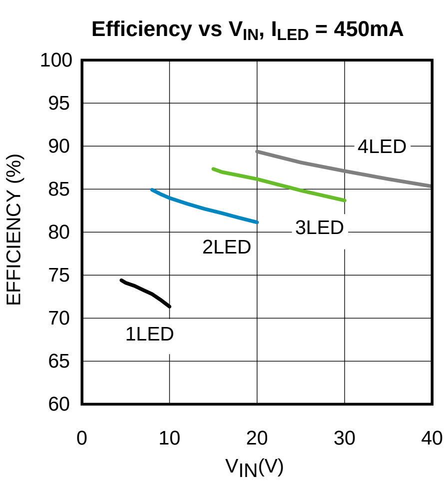


Figure 10.

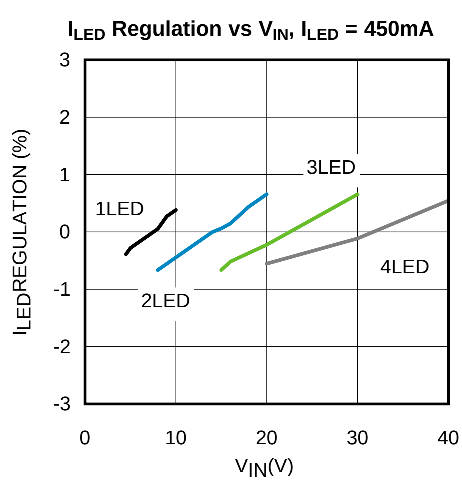


Figure 11.

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

Unless otherwise specified, the following conditions apply: V_{IN} = 48V, C_{IN} is a 2.2µF 100V X7R ceramic capacitor for driving 5–13 power LEDs with I_{LED} = 350mA. Single LED forward voltage used is 3.2V. T_A = 25°C for efficiency curves and waveforms.

Efficiency vs V_{IN}, I_{LED} = 450mA

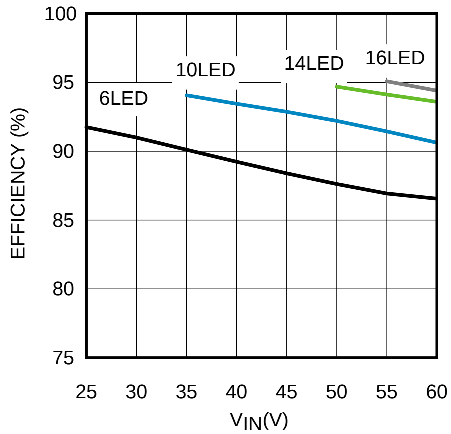


Figure 12.

I_{LED} Regulation vs V_{IN}, I_{LED} = 450mA

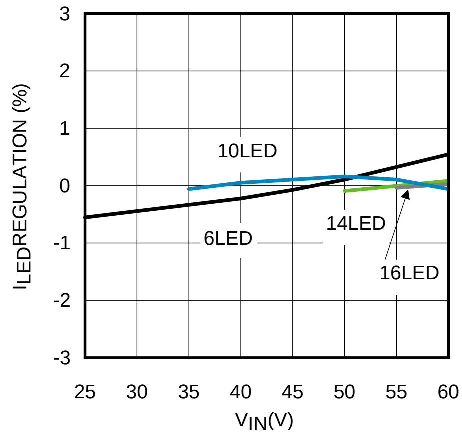


Figure 13.

Efficiency vs V_{IN}, I_{LED} = 300mA

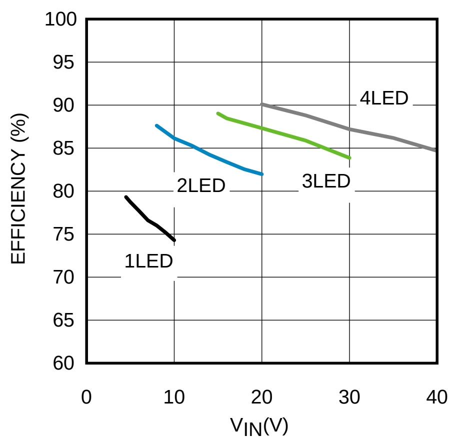


Figure 14.

I_{LED} Regulation vs V_{IN}, I_{LED} = 300mA

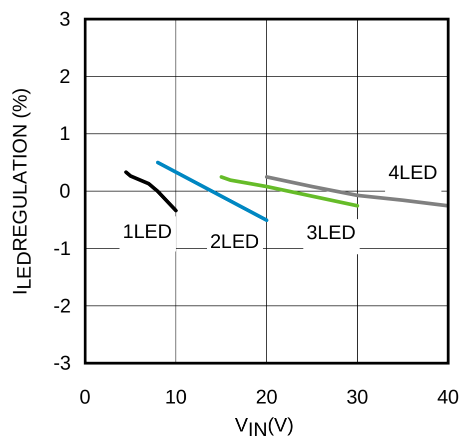


Figure 15.

Efficiency vs V_{IN}, I_{LED} = 300mA

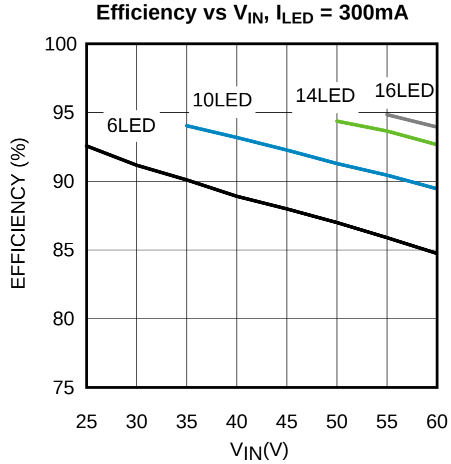


Figure 16.

I_{LED} Regulation vs V_{IN}, I_{LED} = 300mA

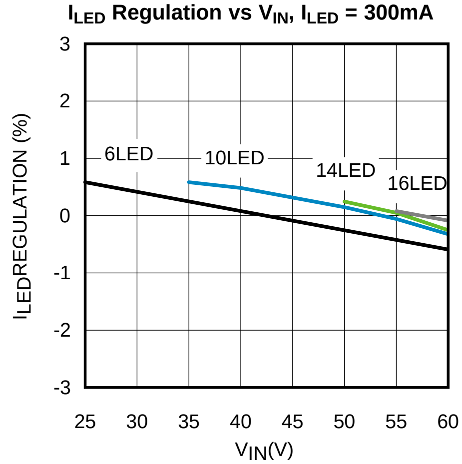


Figure 17.

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

Unless otherwise specified, the following conditions apply: V_{IN} = 48V, C_{IN} is a 2.2µF 100V X7R ceramic capacitor for driving 5–13 power LEDs with I_{LED} = 350mA. Single LED forward voltage used is 3.2V. T_A = 25°C for efficiency curves and waveforms.

LED Current with PWM Dimming V_{DIM} Rising

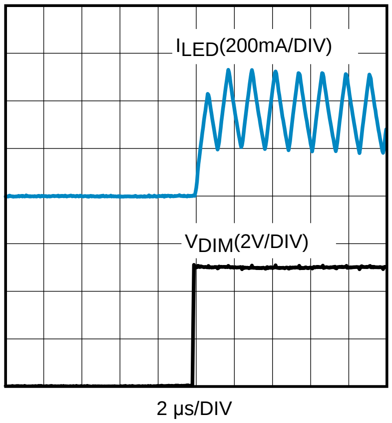


Figure 18.

LED Current with PWM Dimming V_{DIM} Falling

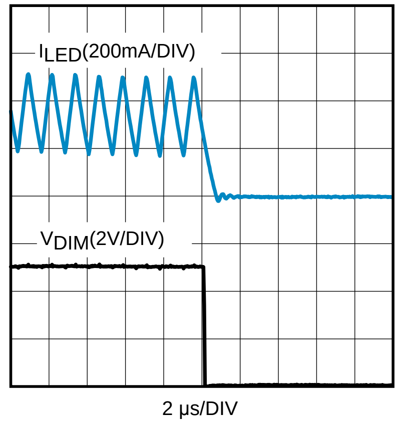


Figure 19.

LED Current with PWM Dimming 16µs dimming pulse

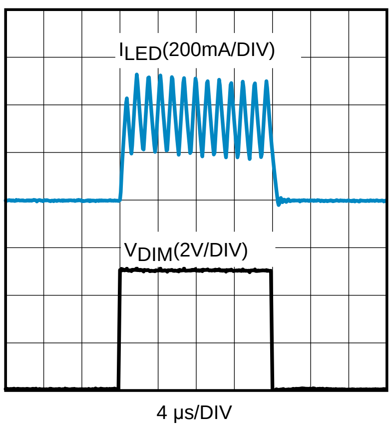


Figure 20.

I_{IN} vs V_{IN} V_{DIM} = 0V

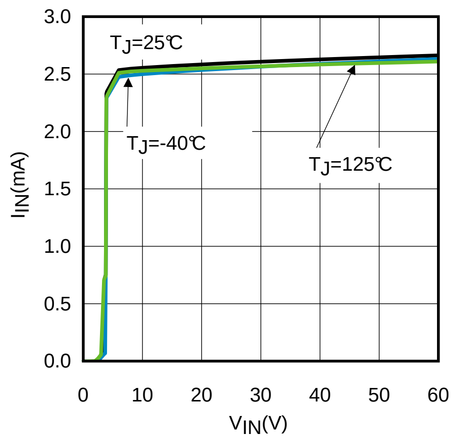


Figure 21.

I_{IN} vs V_{IN} LED = open , DIM = open

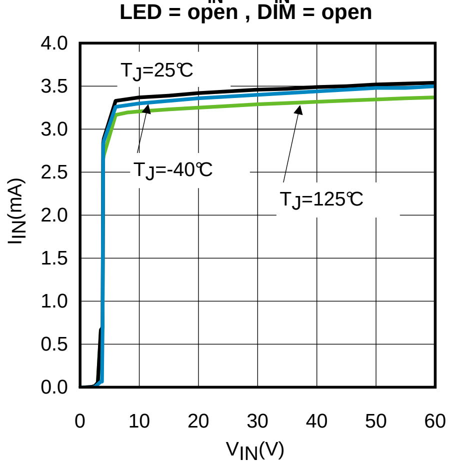


Figure 22.

ILED vs V_{IN} 6LED

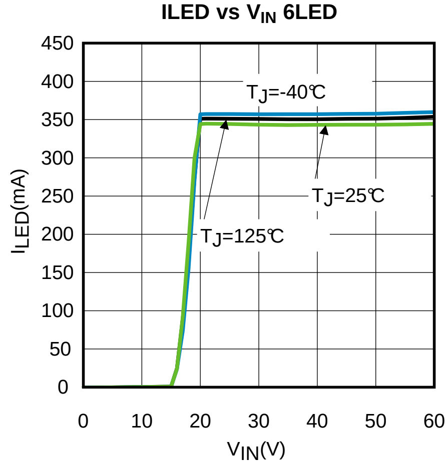


Figure 23.

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

Unless otherwise specified, the following conditions apply: V_{IN} = 48V, C_{IN} is a 2.2µF 100V X7R ceramic capacitor for driving 5–13 power LEDs with I_{LED} = 350mA. Single LED forward voltage used is 3.2V. T_A = 25°C for efficiency curves and waveforms.

I_{LED} vs V_{IN}
V_{LED} = 0V, DIM = open

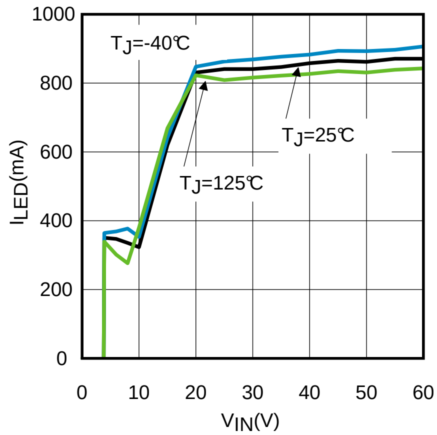


Figure 24.

I_{IN} vs V_{IN}
V_{LED} = 0V, DIM = open

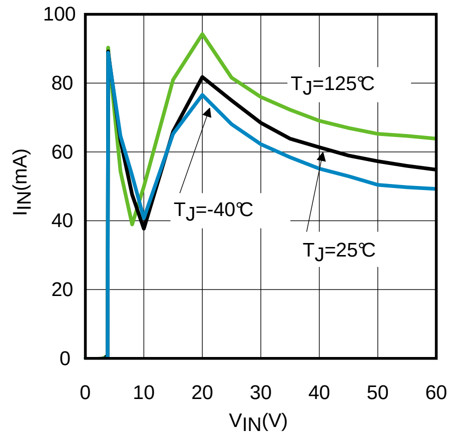


Figure 25.

I_{LED} vs Dimming Duty Ratio

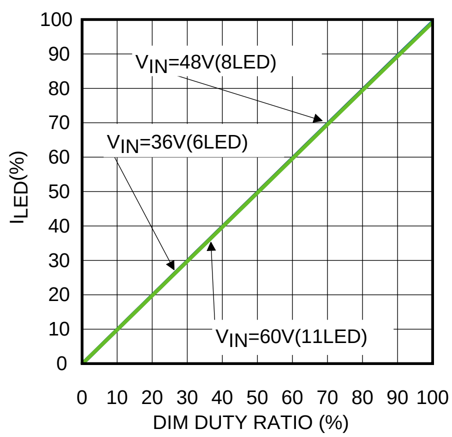


Figure 26.

I_{LED} vs Dimming Duty Ratio

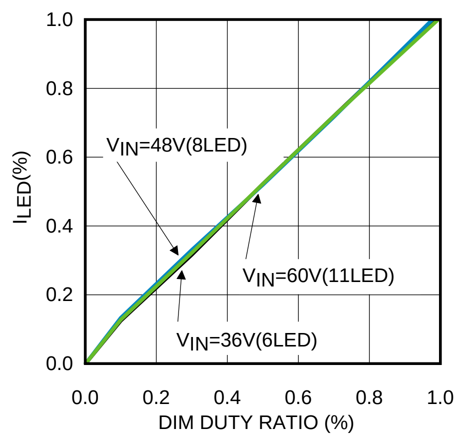


Figure 27.

Frequency Deviation vs V_{IN} (800kHz)

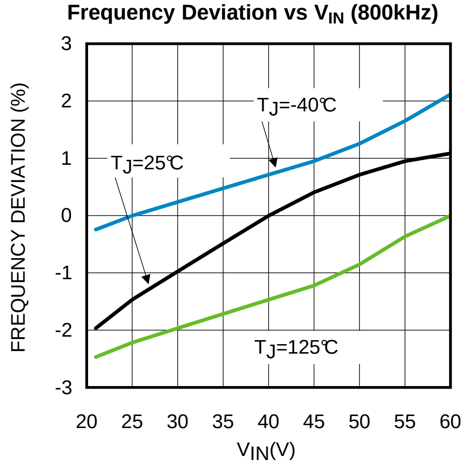


Figure 28.

I_{LED} Regulation vs Temperature

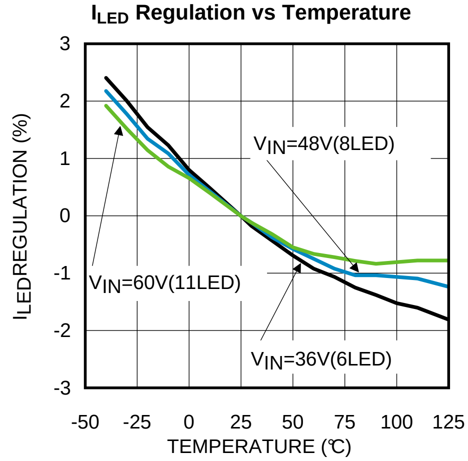


Figure 29.

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

Unless otherwise specified, the following conditions apply: V_{IN} = 48V, C_{IN} is a 2.2µF 100V X7R ceramic capacitor for driving 5–13 power LEDs with I_{LED} = 350mA. Single LED forward voltage used is 3.2V. T_A = 25°C for efficiency curves and waveforms.

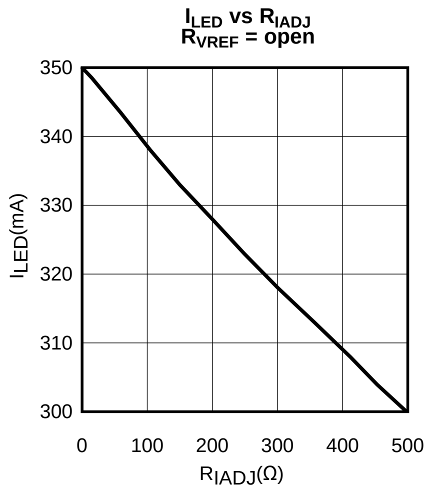


Figure 30.

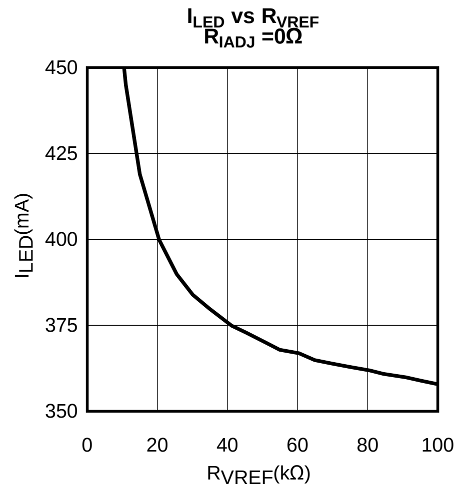
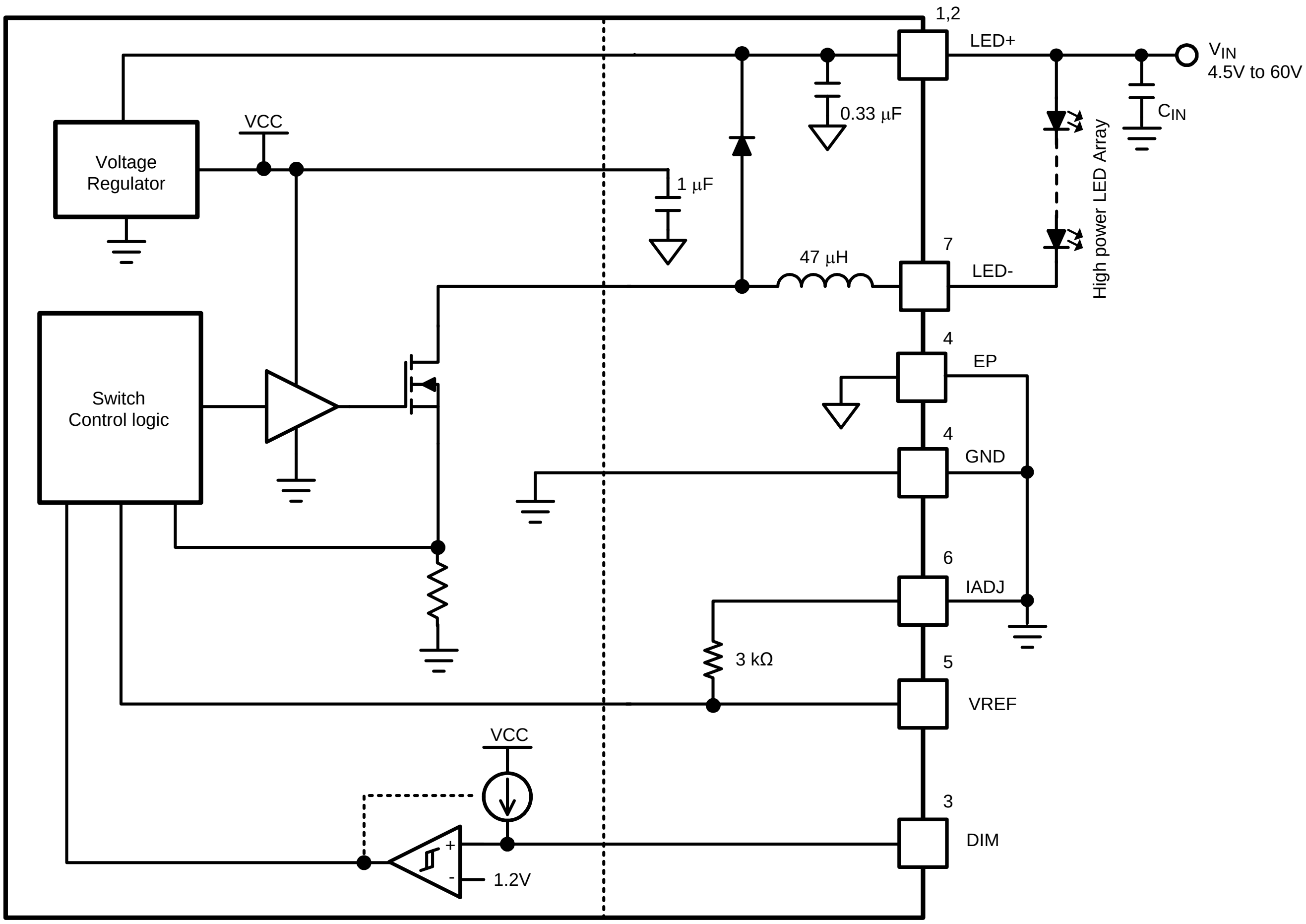


Figure 31.

BLOCK DIAGRAM



OPERATION DESCRIPTION

The TPS92551 is a high power floating buck LED driver with wide input voltage range. It requires no external current sensing elements and loop compensation network. The integrated power switch enables high output power up to 23W with 450mA LED current.

High speed dimming control input allows precision and high resolution brightness control for applications which require fine brightness adjustment.

APPLICATION INFORMATION

SETTING THE LED CURRENT

The TPS92551 requires no external current sensing resistor for LED current regulation. The average LED current of the TPS92551 is adjustable from 300mA to 450mA by varying the resistance of the resistor according to the following equation and table.

For R_{VREF} = open and R_{IADJ} <=499Ω

$$I_{LED} = \frac{1050}{3k + R_{IADJ}} \quad (1)$$

For R_{IADJ} = 0 and R_{VREF} >= 10.5kΩ

$$I_{LED} = \frac{1050}{3k // R_{VREF}} \quad (2)$$

Table 1. Example for I_{LED} Setting

R_{IADJ}(Ω)	R_{VREF}(Ω)	I_{LED}(mA)
499	OPEN	300
SHORT	OPEN	350
SHORT	10.5k	450

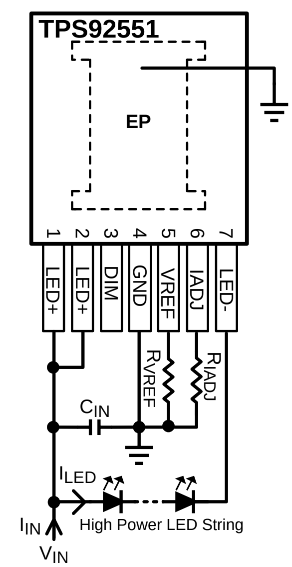


Figure 32. TPS92551 Application Schematic for I_{LED} Setting

Minimum Switch On-Time

The on-time of the internal switch should be no shorter than 400ns. The number of LED (typical forward voltage at 3.2V) to input voltage is constrained by that as shown in the following table.

No. of LED	Max. V_{IN}(V)
1	10
2	20
3	30
4	40
5	50
6 – 16	60

Peak Switch Current Limit

The TPS92551 features an integrated switch current limiting mechanism to prevent the LEDs from being over-driven. The switch current limiter is triggered when the switch current is three times exceeding the current level set by resistor. Once the current limiter is triggered, the internal power switch turn OFF for 3.6µs to discharge the inductor until inductor current reduces back to normal level. The current limiting feature is exceptionally important to avoid permanent damage of the TPS92551 application circuit due to short circuit of LED string.

PWM Dimming Control

The DIM pin of the TPS92551 is an input with internal pull-up that accepts logic signals for average LED current control. Applying a logic high (above 1.3V) signal to the DIM pin or leaving the DIM pin open will enable the device. Applying a logic low signal (below 0.7V) to the DIM pin will disable the switching activity of the device but maintain operation of the VCC regulator active. The TPS92551 operation of high speed dimming and very fine dimming control as shown in Figure 33.

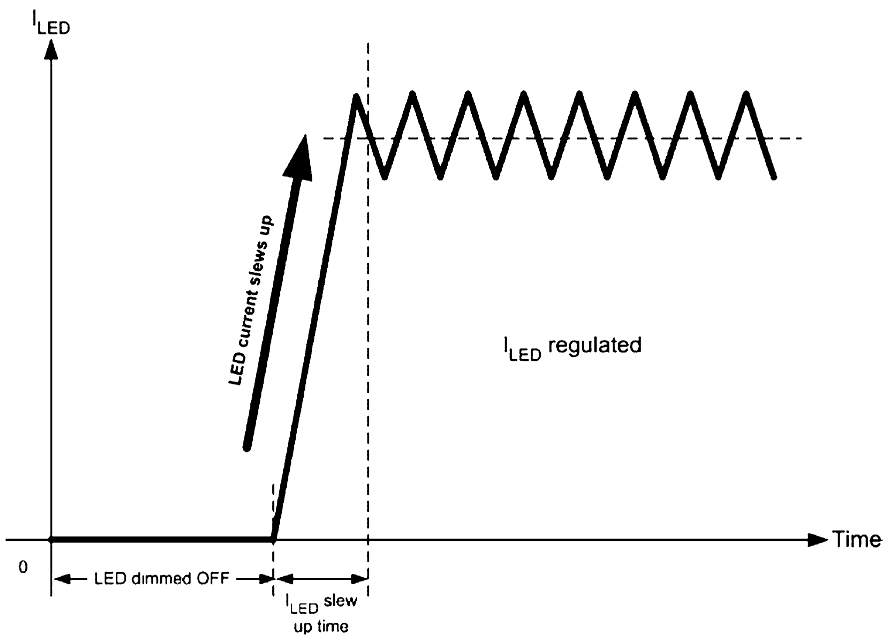


Figure 33. Shortened Current Slew up Time of the TPS92551

To ensure normal operation of the TPS92551, it is recommended to set the dimming frequency not higher than 1/10 of the switching frequency. The dim pulse on time is tested down to 16µs. In applications that require high dimming contrast ratio, low dimming frequency should be used.

Parallel Operation

When a load current higher than 450mA is required by the application, TPS92551 can be used in parallel to deliver higher current. With common VINs and GNDs, the TPS92551 will operate as independent asynchronous current sinks driving the same LED load. The total DC current of the modules will be additive; however, low frequency sub-harmonic current ripple may be present and its frequency and magnitude will depend upon the phase relationship between the internal clocks as there is no provision for synchronizing driver clocks. It is suggested to have minimum 2.2µF C_{OUT} located close the module to filter out the current ripple , and the resultant LED current will become DC. Current sharing modules should have a local C_{IN} capacitor of minimum 2.2µF located as close to V_{IN} and GND as possible. Refer to Figure 33 for the TPS92551 parallel operation circuit schematic. Refer to Figure 35 for the TPS92551 parallel operation results I_{LED} vs V_{IN}.

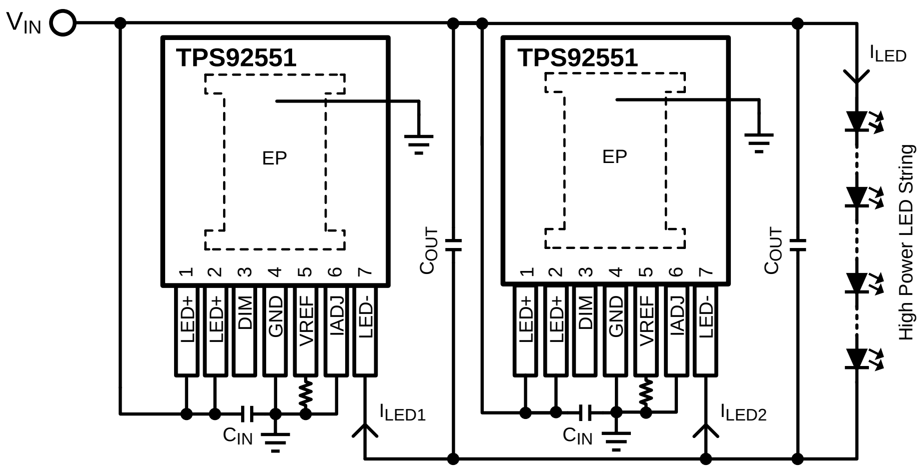


Figure 34. Parallel Operation Circuit Schematic for I_{LED} = 900mA

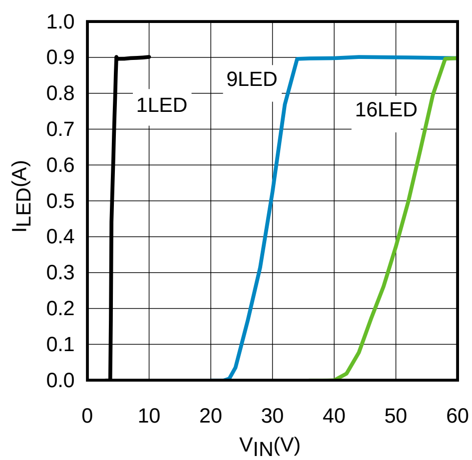


Figure 35. Parallel Operation Results for I_{LED} = 900mA, I_{LED} vs V_{IN}

PC Board Layout Considerations

The overall performance of the LED driver is highly depends on the PCB layout. Poor board layout can disrupt the performance of the TPS92551 and surrounding circuitry by contributing to EMI, ground bounce and resistive voltage drop in the traces. These can send erroneous signals to the LED driver resulting in poor regulation and stability. Good layout can be implemented by following a few simple design rules.

1. Place C_{IN} as close as possible to the V_{IN} pin and GND exposed pad (EP).
2. Place C_{OUT} (optional for reduction of LED current ripple and EMI compliance) as close as possible to the VLED+ pin and VLED- pin.
3. The exposed pad (EP) must connect to the GND pin directly.

EMI Design Considerations

From an EMI reduction standpoint, it is imperative to minimize the di/dt current paths (refer to Figure 36). Therefore, it is essential to connect an 2.2µF capacitor (C_{OUT}) across the LED+ pin and LED- pin. This will minimize the ripple current so that it can reduce radiated EMI (refer to Figure 37 and Figure 38).

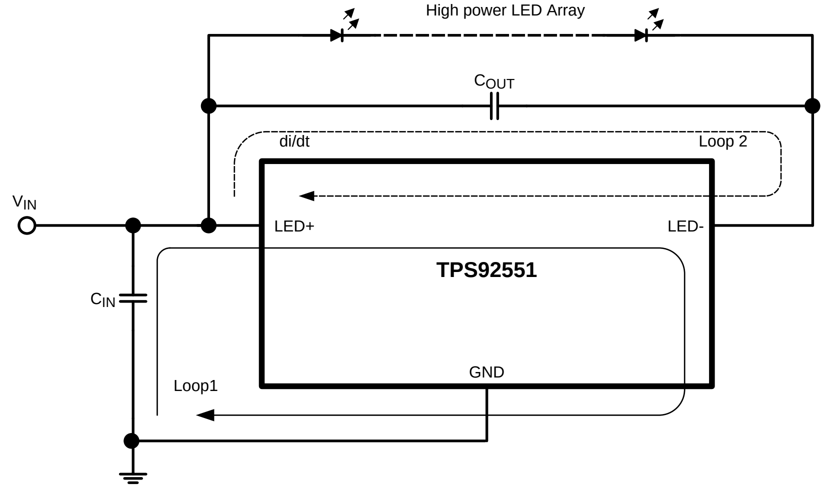


Figure 36. Current Loops

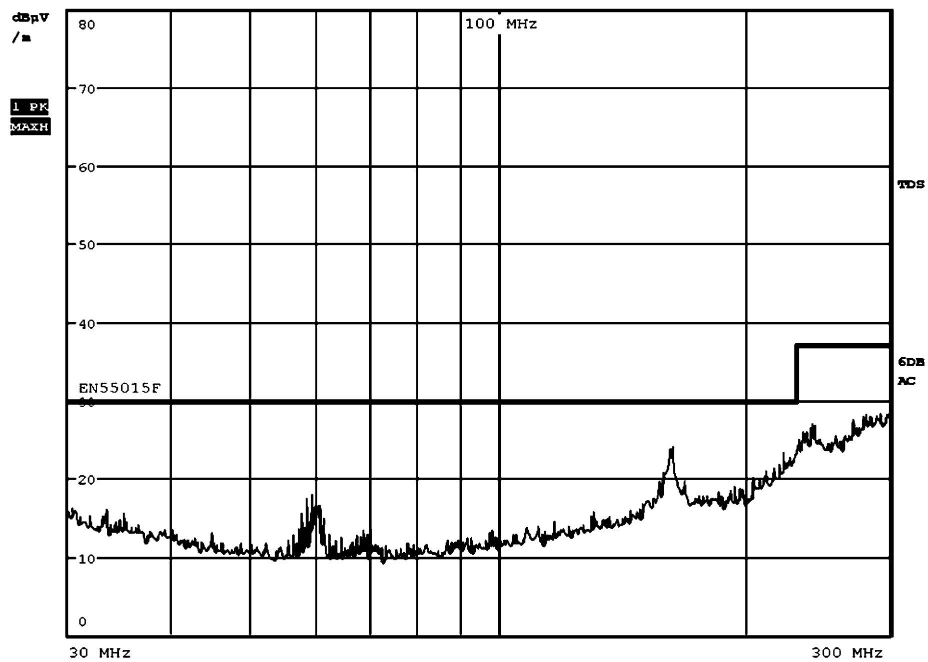


Figure 37. Complies with EN55015 Radiated Emissions (HORI. / HEIGHT=3.0m / RANGE=10m)
C_{IN} = 2.2uF, C_{OUT} = 2.2μF, V_{IN} = 60V, I_{LED} = 350mA, No. of LED = 16

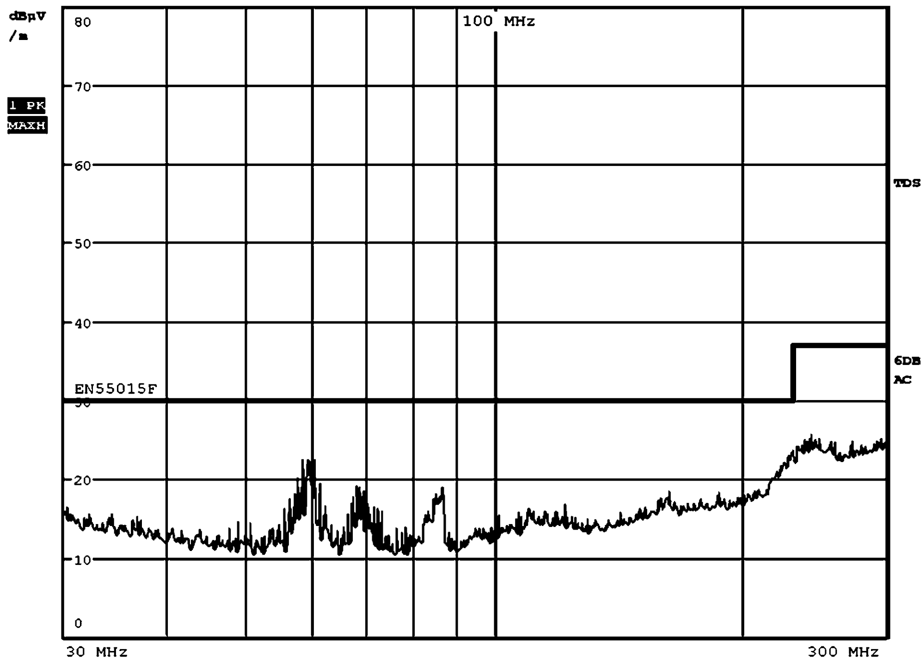


Figure 38. Complies with EN55015 Radiated Emissions (VERT. / HEIGHT=1.0m / RANGE=10m) C_{IN} = 2.2uF, C_{OUT} = 2.2µF, V_{IN} = 60V , I_{LED} = 350mA, No. of LED = 16

TPS92551 Application Circuit Schematic and BOM

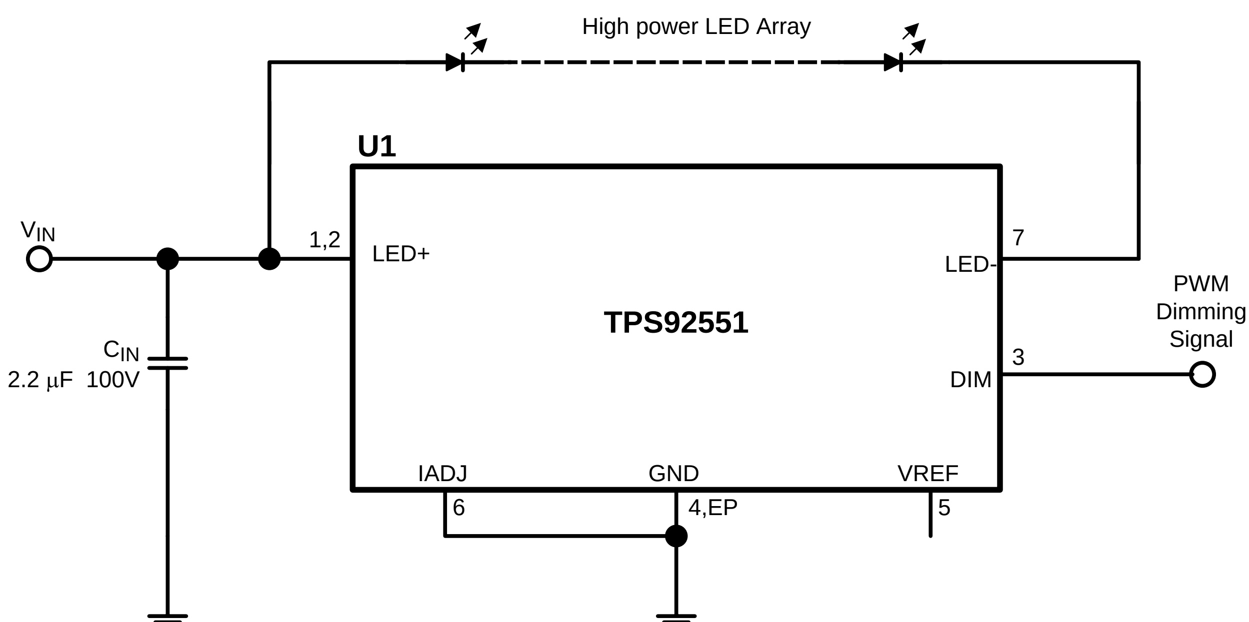


Table 2. Bill of Materials, V_{IN} = 48V , I_{LED} = 350mA, No. of LED = 5 –13

Designator	Description	Case Size	Manufacturer	Manufacturer P/N	Quantity
U1	LED Micro-Module Driver	PFM	Texas Instruments	TPS92551TZ	1
C_{IN}	2.2 µF, 100V, X7R	1210	Murata	GRM32ER72A225KA35L	1

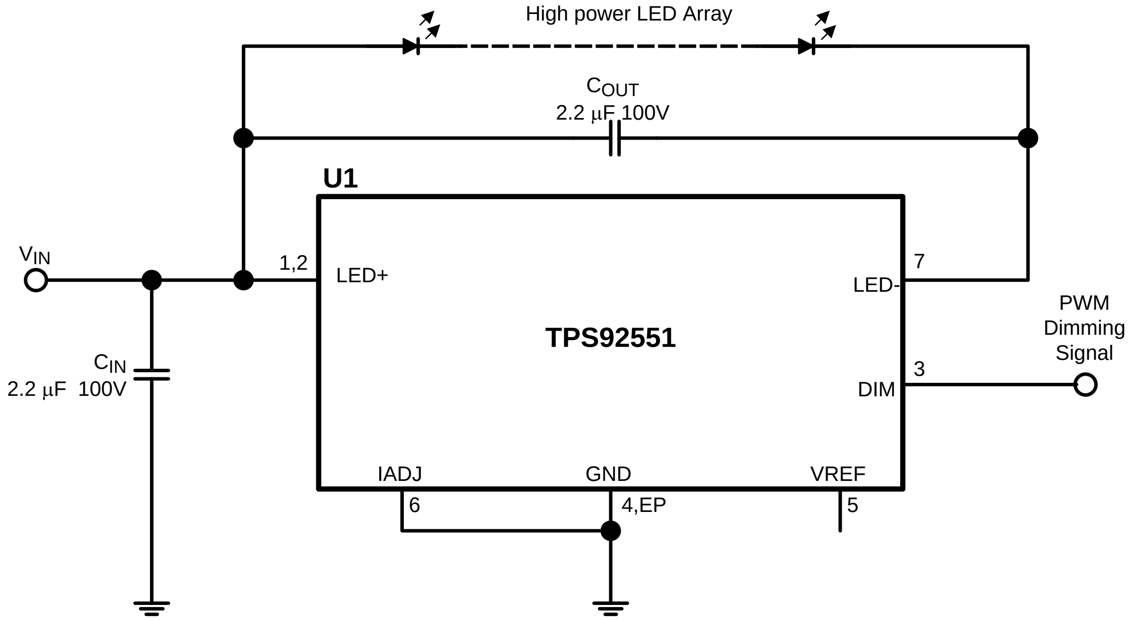


Table 3. Bill of Materials, V_{IN} = 60V , I_{LED} = 350mA , No.of LED = 16, Complies with EN55015 Radiated Emissions

Designator	Description	Case Size	Manufacturer	Manufacturer P/N	Quantity
U1	LED Micro-Module Driver	PFM	Texas Instruments	TPS92551TZ	1
C_{IN}	2.2 µF, 100V, X7R	1210	Murata	GRM32ER72A225KA35L	1
C_{OUT}	2.2 µF, 100V, X7R	1210	Murata	GRM32ER72A225KA35L	1

PCB Layout Diagrams

The PCB design is available in the TPS92551 product folder at www.ti.com.

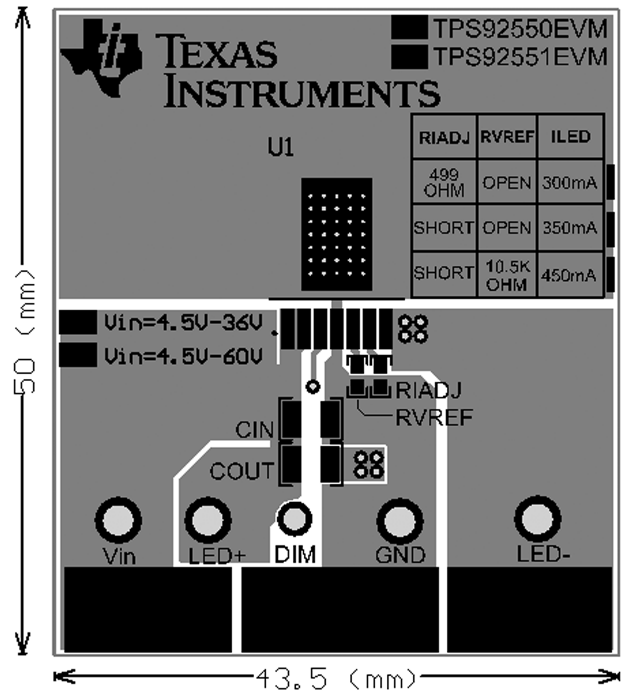


Figure 39. Top Layer and Top Overlay

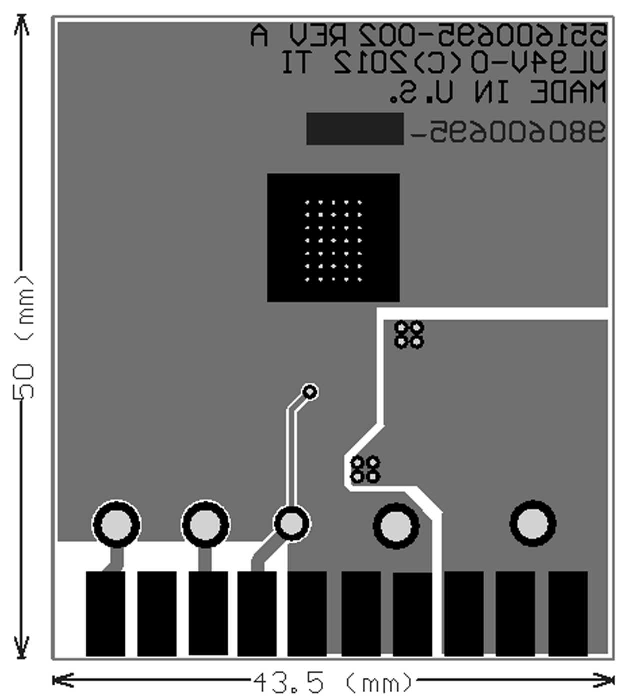


Figure 40. Bottom Layer and Bottom Overlay

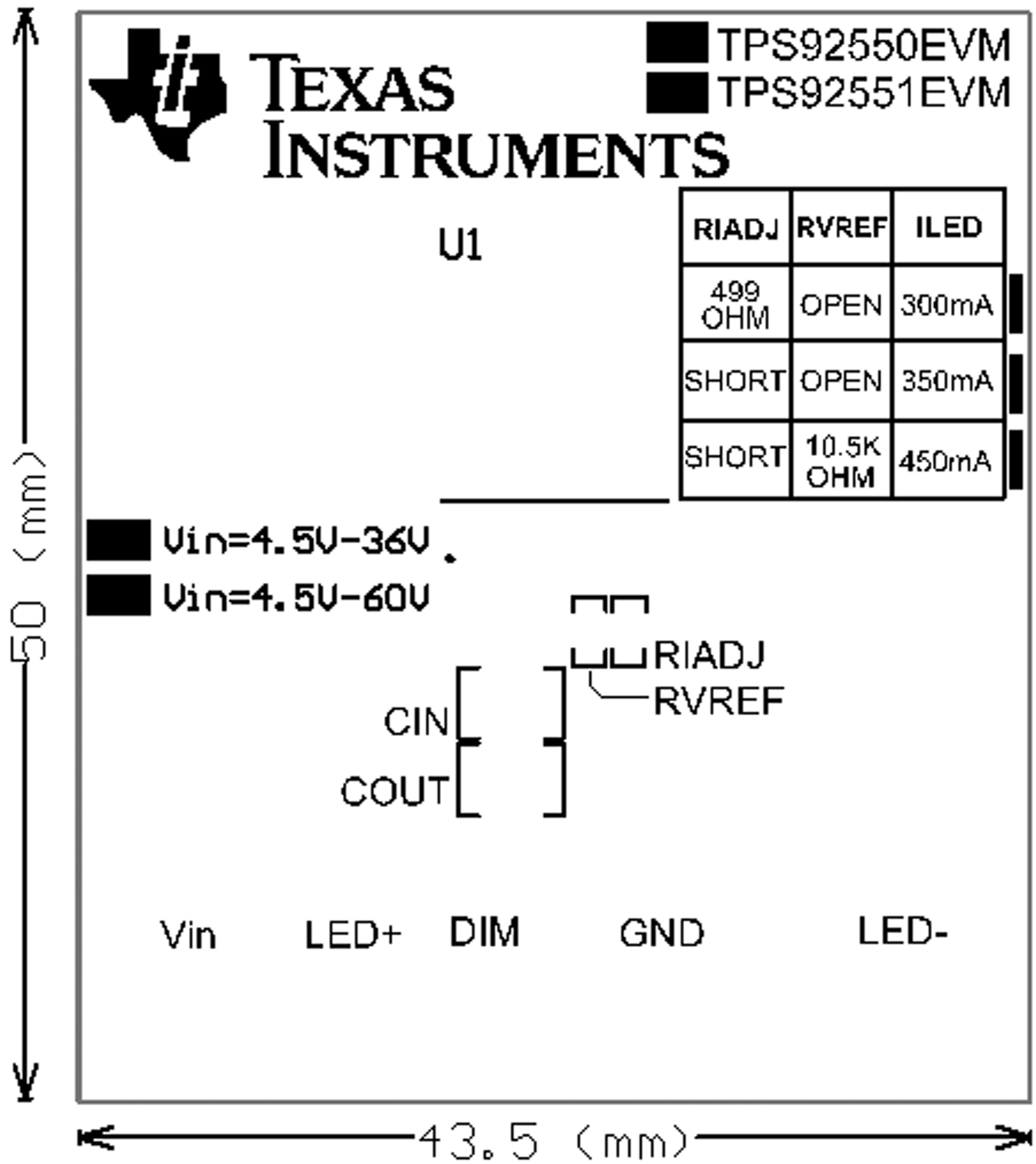


Figure 41. Top Overlay

REVISION HISTORY

Changes from Revision B (May 2013) to Revision C	Page
• Changed layout of National Data Sheet to TI format	19

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS92551TZ/NOPB	ACTIVE	TO-PMOD	NDW	7	250	Green (RoHS & no Sb/Br)	SN	Level-3-245C-168 HR	-40 to 125	TPS92551 TZ	Samples
TPS92551TZX/NOPB	ACTIVE	TO-PMOD	NDW	7	500	Green (RoHS & no Sb/Br)	SN	Level-3-245C-168 HR	-40 to 125	TPS92551 TZ	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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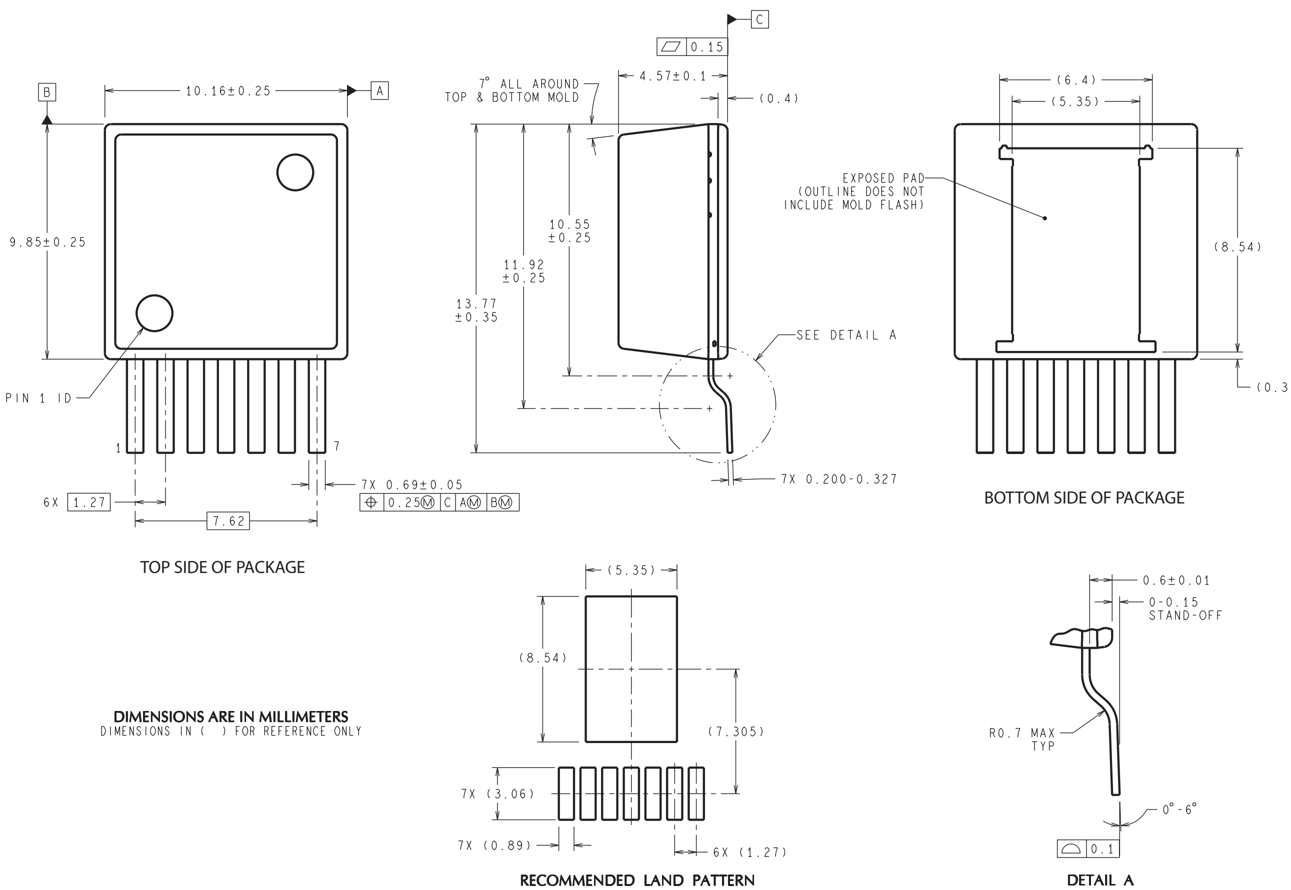

TZA07A (Rev D)

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